

TSB80R240S1

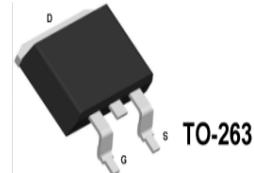
800V 20A N-Channel SJ-MOSFET

General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

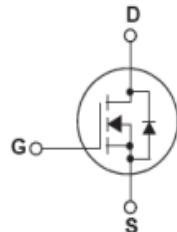
This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.



Features

- 850V @ $T_J = 150\text{ }^{\circ}\text{C}$
- Typ. RDS(on) = 0.22Ω
- Ultra Low gate charge (typ. Qg = 70nC)
- 100% avalanche tested



Absolute Maximum Ratings

Symbol	Parameter	TSB80R240S1	Unit
V _{DSS}	Drain-Source Voltage	800	V
I _D	Drain Current -Continuous (TC = 25°C) -Continuous (TC = 100°C)	20 10	A
I _{DM}	Drain Current – Pulsed (Note 1)	62	A
V _{GSS}	Gate-Source voltage	±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	485	mJ
I _{AR}	Avalanche Current (Note 1)	3.5	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P _D	Power Dissipation (TC = 25°C) -Derate above 25°C	206 1.67	W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	°C

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.6	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink Typ.	0.5	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62	°C/W

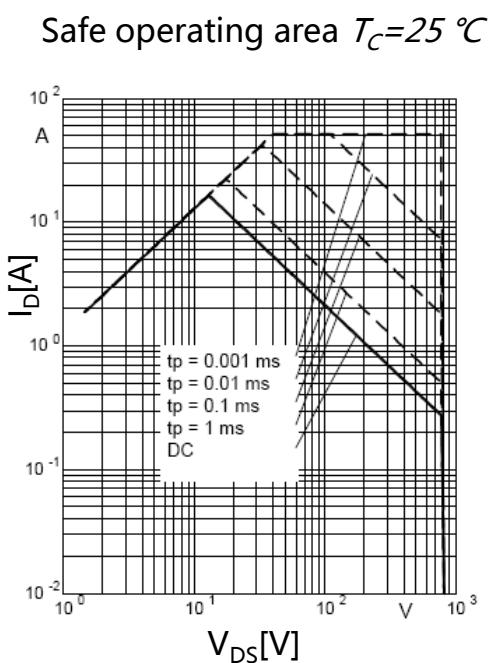
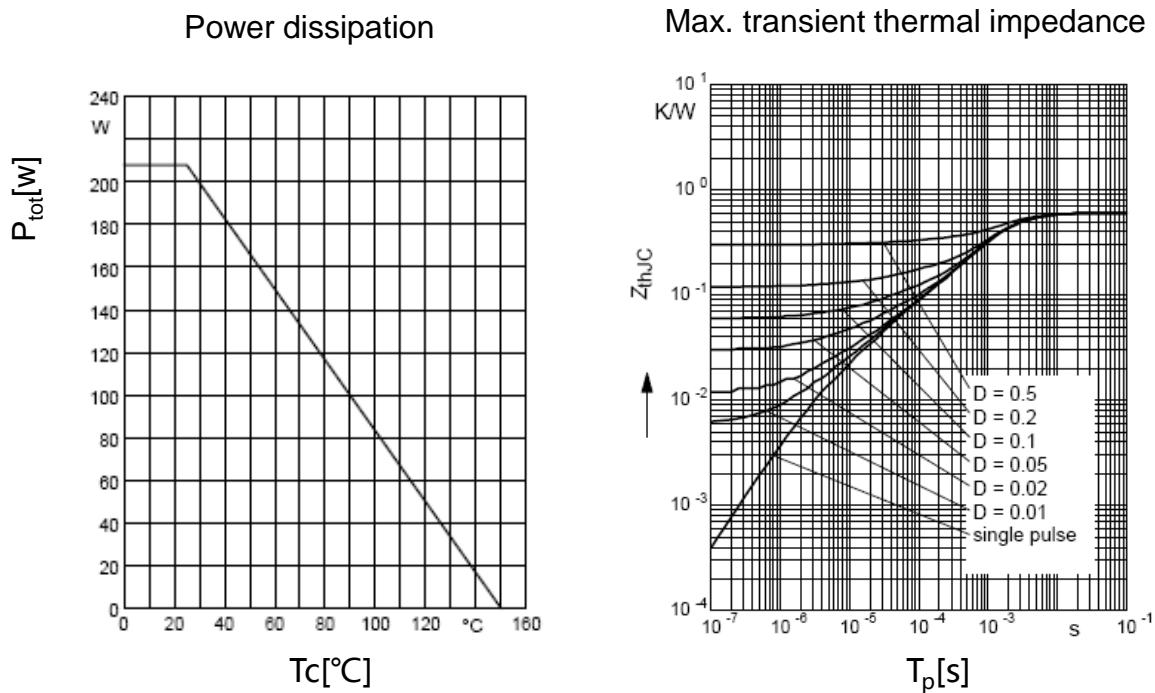
Electrical Characteristics TC = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	800	--	--	V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^\circ C$	--	850	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to $25^\circ C$	--	0.6	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 800V, V_{GS} = 0V, T_C = 25^\circ C$ $-T_C = 125^\circ C$	--	--	1	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 5A$	--	0.22	0.24	Ω
g_{FS}	Forward Trans conductance	$V_{DS} = 40V, I_D = 5A$ (Note 4)	--	16	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	--	1440	--	pF
C_{oss}	Output Capacitance		--	300	--	pF
C_{rss}	Reverse Transfer Capacitance		--	10	--	pF
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400V, I_D = 5A$ $R_G = 20\Omega$ (Note 4 , 5)	--	25	--	ns
t_r	Turn-On Rise Time		--	55	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	70	--	ns
t_f	Turn-Off Fall Time		--	40	--	ns
Q_g	Total Gate Charge	$V_{DS} = 480V, I_D = 10A$ $V_{GS} = 10V$ (Note 4,5)	--	70	90	nC
Q_{gs}	Gate-Source Charge		--	7.8	--	nC
Q_{gd}	Gate-Drain Charge		--	9	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain-Source Diode Forward Current		--	--	20	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	60	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_F = 10A$	--	1	1.5	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_F = 10A$ $di_F/dt = 100A/\mu s$ (Note 4)	--	475	--	ns
Q_{rr}	Reverse Recovery Charge		--	5.8	--	μC

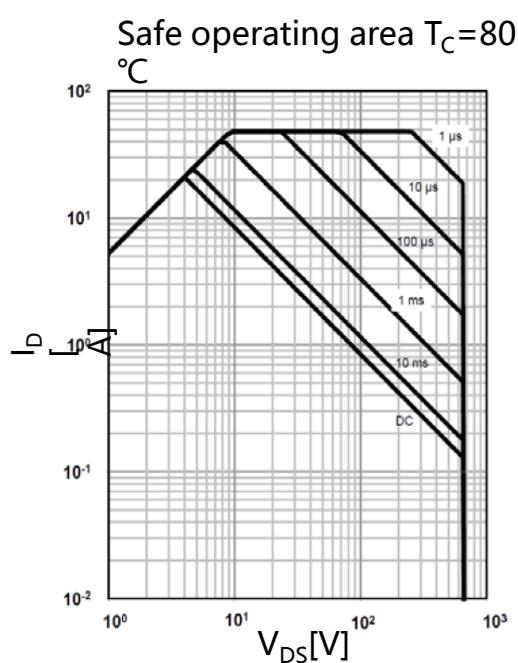
NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 79mH, I_{AS} = 3.5A, V_{DD} = 50V$, Starting $T_J = 25^\circ C$
3. $I_{SD} \leq 20A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ C$
4. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

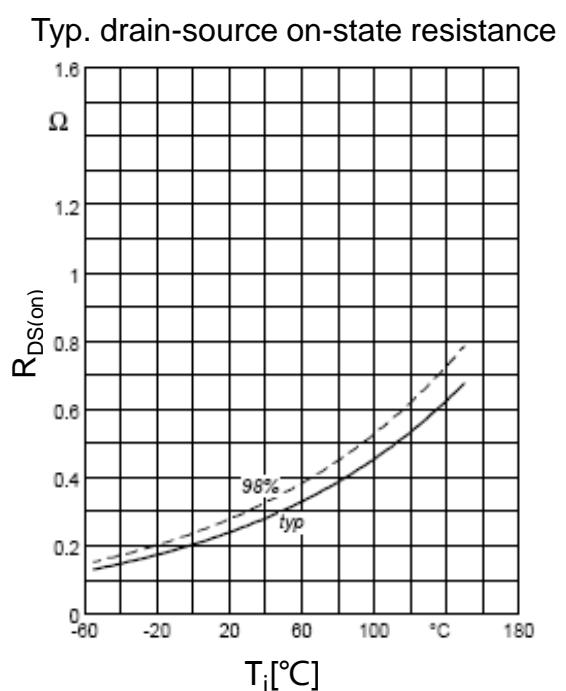
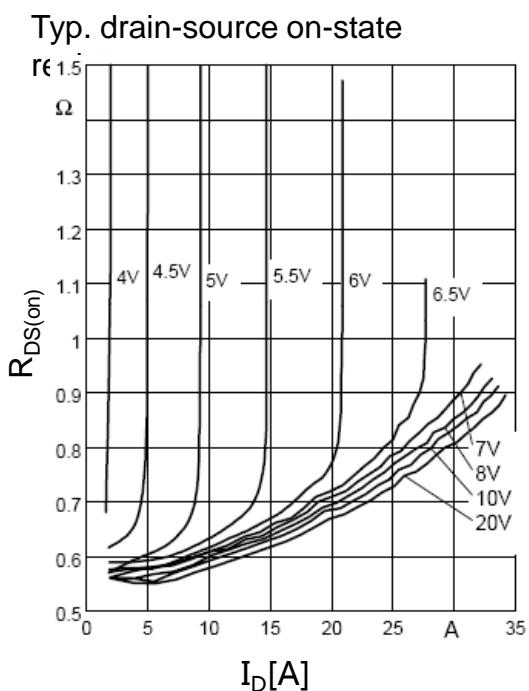
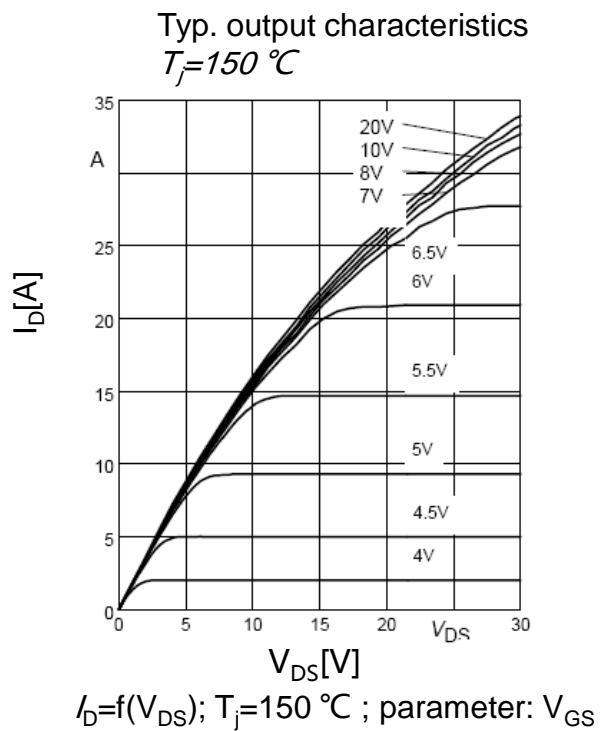
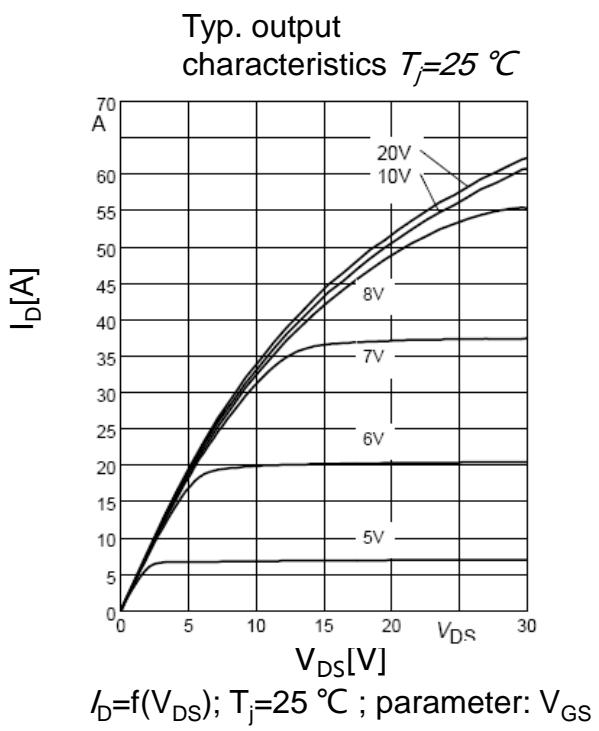


$I_D=f(V_{DS})$; $T_C=25\text{ }^\circ\text{C}$; $V_{GS} > 7\text{V}$;
D=0; parameter t_p

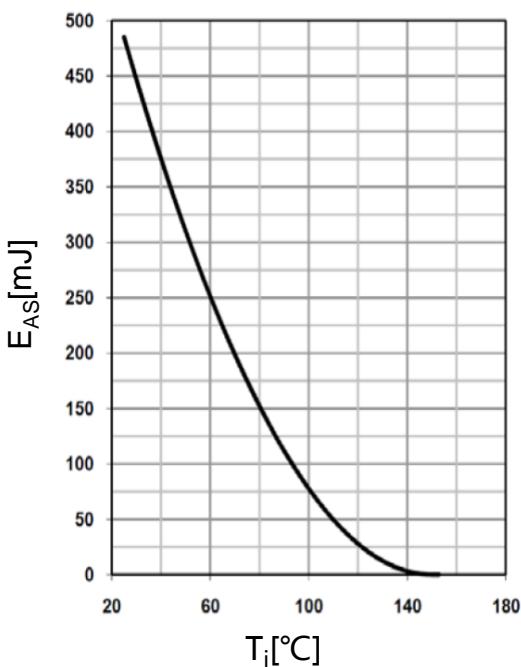
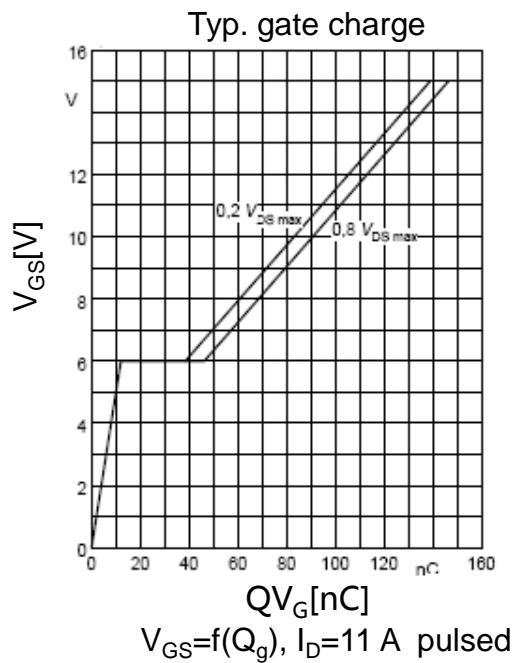
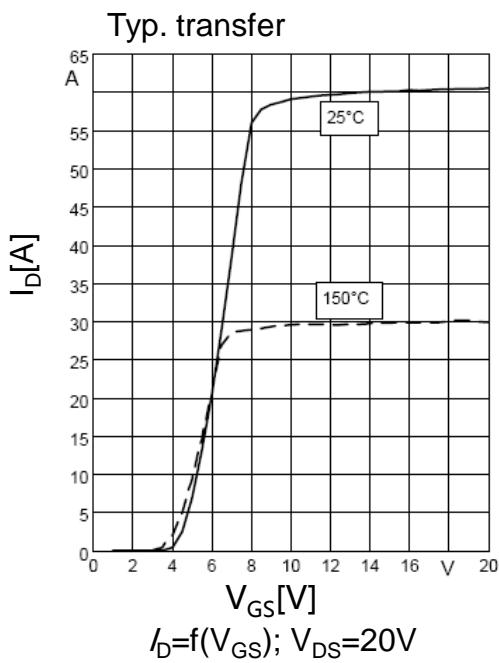


$I_D=f(V_{DS})$; $T_C=80\text{ }^\circ\text{C}$; $V_{GS} > 7\text{V}$;
D=0; parameter t_p

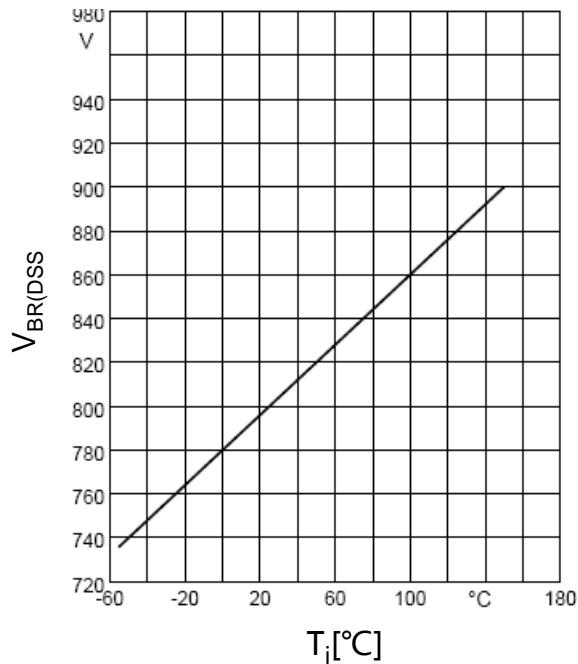
Typical Performance Characteristics



Typical Performance Characteristics

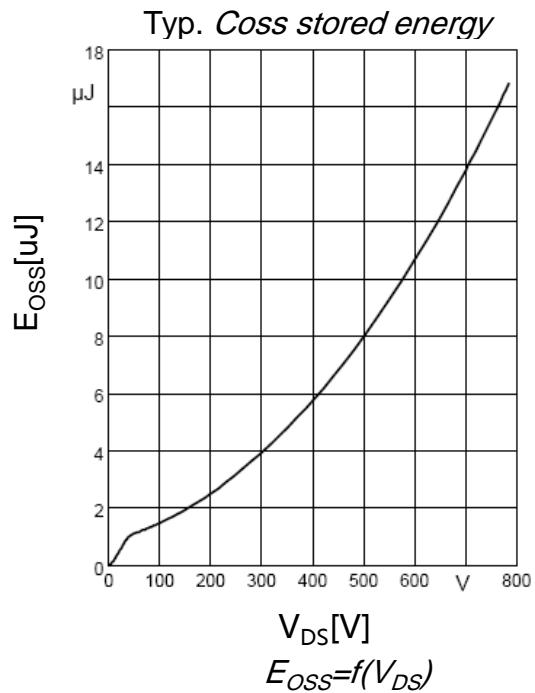
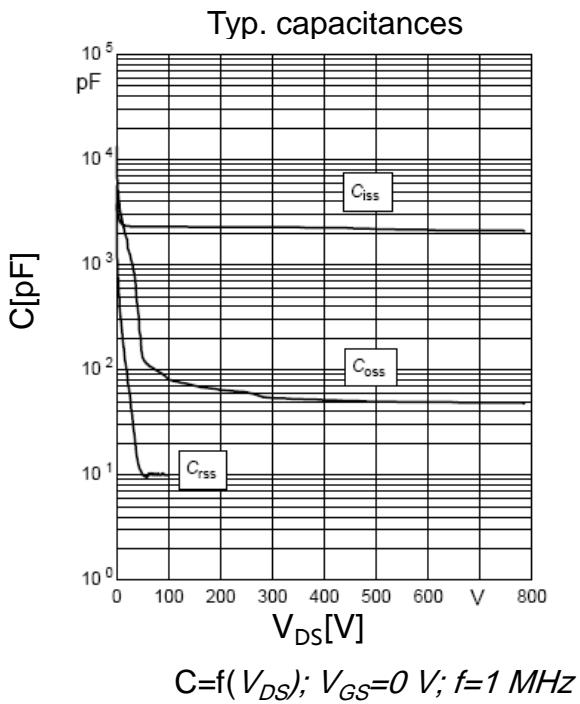


$E_{AS} = f(T_j)$; $I_D = 3.5 A$; $V_{DD} = 50 V$

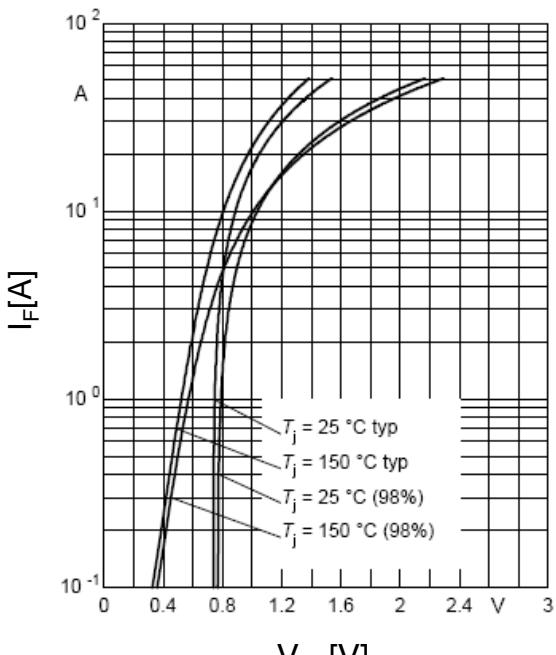


$V_{BR(DSS)} = f(T_j)$; $I_D = 1.0 mA$

Typical Performance Characteristics



Forward characteristics of reverse diode

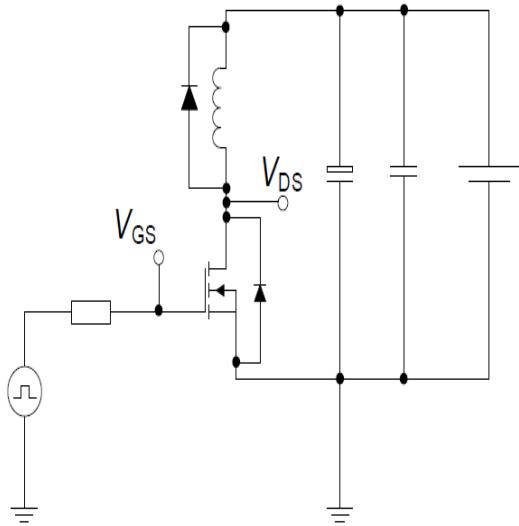


$$I_F = f(V_{SD}); \text{ parameter: } T_j$$

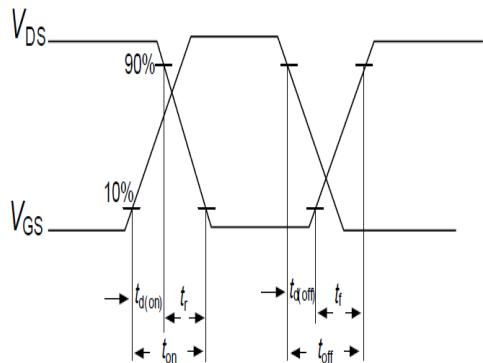
Test circuits

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

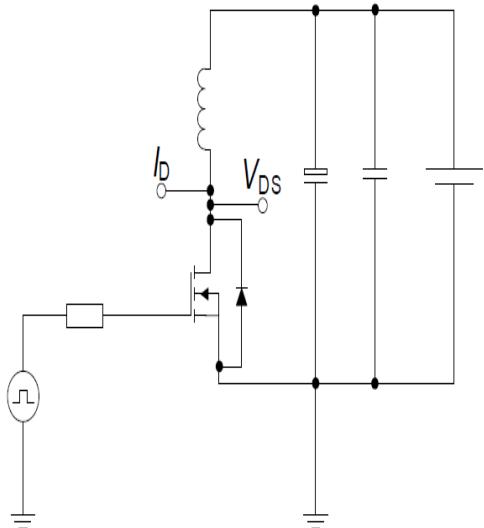


Switching time waveform

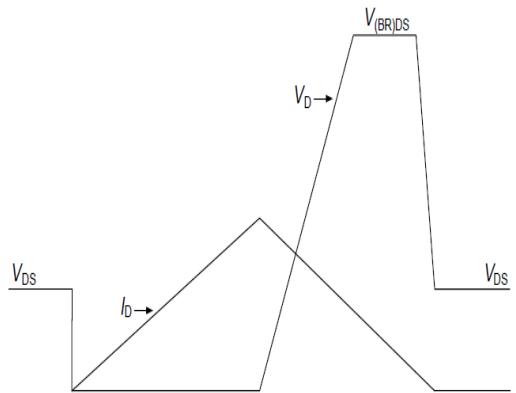


Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit

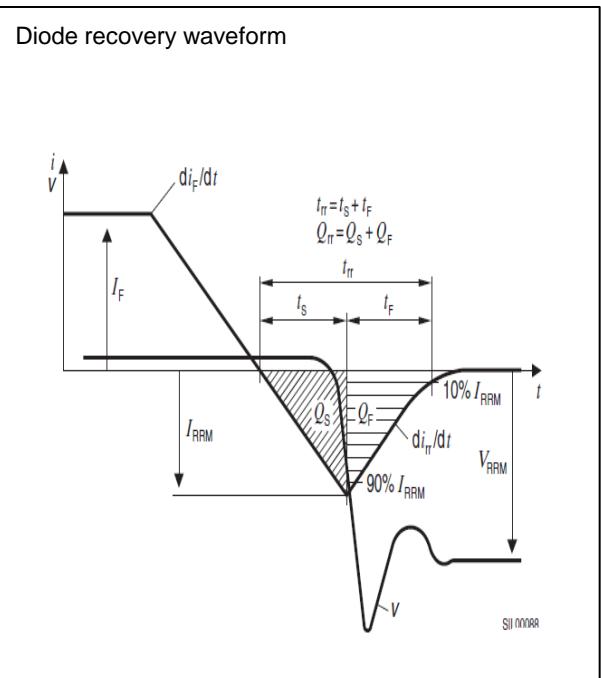
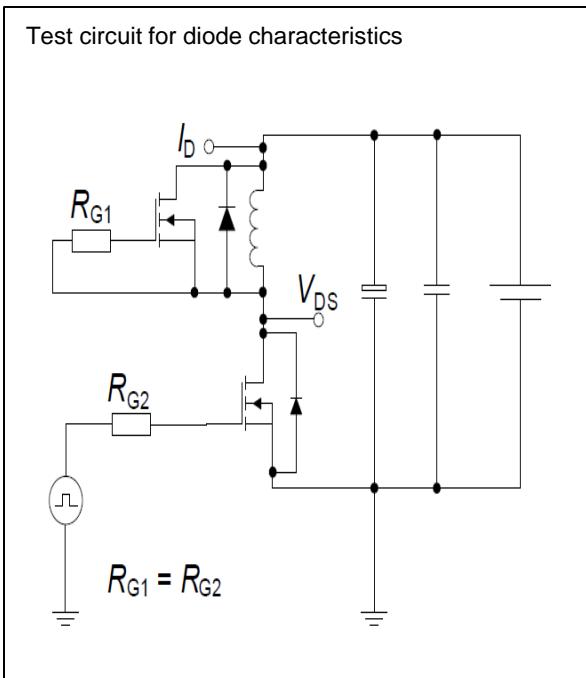


Unclamped inductive waveform

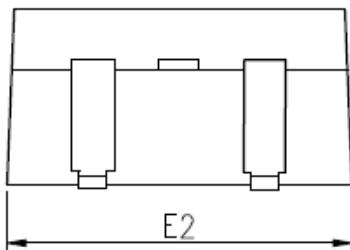
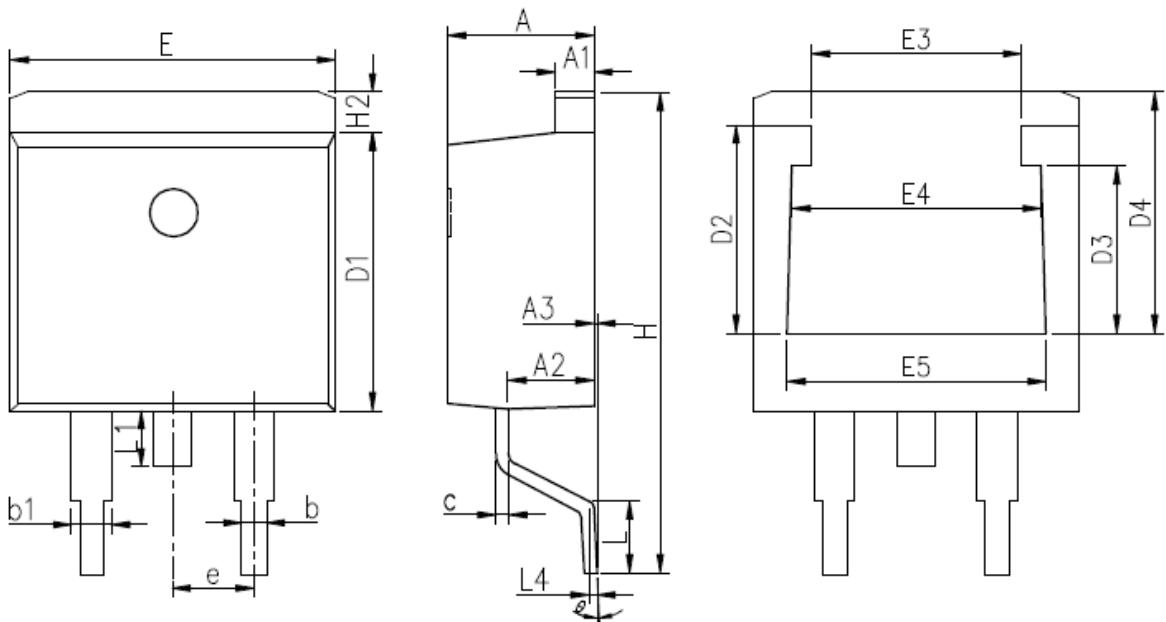


Test circuits

Test circuit and waveform for diode characteristics



Package Outline TO-263



COMMON DIMENSIONS

SYMBOL	MM		
	MIN	NOM	MAX
A	4.27	4.57	4.87
A1	1.22	1.27	1.42
A2	2.39	2.69	2.99
A3	0.00	0.13	0.20
b	0.70	0.81	1.01
b1	1.17	1.27	1.50
c	0.30	0.38	0.53
D1	8.40	8.70	9.00
D2	5.33	6.33	6.63
D3	4.54	5.54	5.84
D4	6.60	7.60	8.00
E	9.88	10.16	10.50
E2	9.80	10.10	10.40
E3	4.94	5.94	6.24
E4	6.67	7.67	7.97
E5	7.06	8.06	8.36
e		2.54	BSC
H	14.70	15.10	15.50
H2	1.00	1.27	1.50
L	2.00	2.30	2.60
L1	1.35	1.55	1.75
L4		0.25	BSC
θ	0°	5°	9°